

## 100% Material Declaration Data Sheet BG352

### PK195 (v1.0.1) January 8, 2007

Material Declaration Data Sheet

### Average Weight: 7.142g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0291	0.41%
	Silicon	7440-21-3	100.00		0.0291	
Die Attach Material					0.004	0.06%
	Resin	Trade Secret	25.00		0.001	
	Silver	7440-22-4	75.00		0.003	
Mold Compound					0.2374	3.32%
	Resin	Trade Secret	26.00		0.062	
	Silica	60676-86-0	74.00		0.176	
Dam					0.0088	0.12%
	Proprietary	Trade Secret	27.00			
	Silica	60676-86-0	73.00			
Laminate					0.647	9.06%
	Copper	7440-50-8		Metal Layer	0.101	
	Nickel	7440-02-0		Metal Layer	0.006	
	Gold	7440-57-5		Metal Layer	0.002	
	Board	Trade Secret			0.396	
	Solder Mask (EP)	Trade Secret			0.142	
Heat Sink					5.252	73.54%
	Copper	7440-50-8	100.00		5.252	
Heat Sink Plating					0.2243	3.14%
	Nickel	7440-02-0	100.00		0.2243	
Gold Wire					0.0224	0.31%
	Gold	7440-57-5	100.00		0.0224	
Solder Balls					0.717	10.04%
	Tin	7440-31-5	63.00		0.452	
	Lead	7439-92-1	37.00		0.265	

#### PK195 (v1.0.1) January 8, 2007

#### www.xilinx.com

© 2006, 2007 Xilinx, Inc. All rights reserved. All Xilinx trademarks, registered trademarks, patents, and disclaimers are as listed at <a href="http://www.xilinx.com/legal.htm">http://www.xilinx.com/legal.htm</a>. All other trademarks and registered trademarks are the property of their respective owners. All specifications are subject to change without notice. Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

www.BDTIC.com/XILINX

# **Revision History**

Date Revision		Revision
10/5/06	1.0	Initial release.
1/8/07	1.0.1	Corrected Gold Wire CAS# entry.

The following table shows the revision history for this document.

